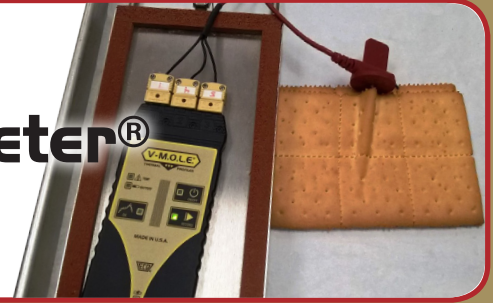


For Bake Cycle
Perfection Every Time

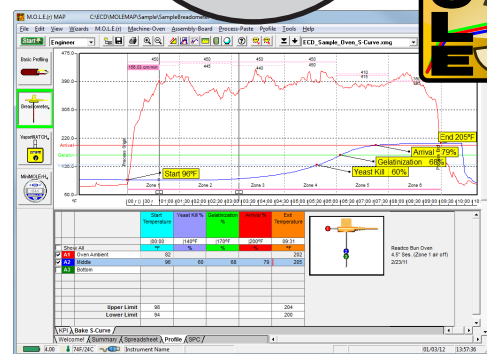
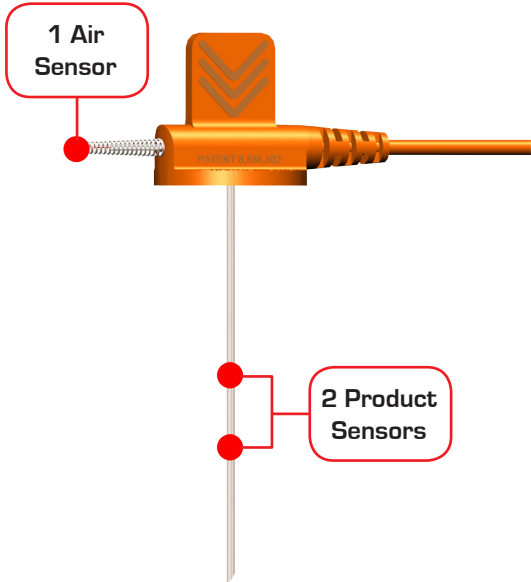
Breadometer®



Breadometer® solves the problem of over and under-baked products and provides data to properly adjust the oven to produce an S-Curve that optimizes Crumb Set and moisture content. This unique, patented one-piece probe is designed to measure internal dough temperatures at two consistent depths with the BakeWATCH V-M.O.L.E.® and the Bake-S-Curve feature in the Breadometer Environment of M.O.L.E.®MAP software.

Rather than relying upon an operator to repeatedly insert individual thermocouples, then manually analyze inconsistent data, Breadometer automatically calculates Yeast Kill, Starch Gelatinization and Arrival to baking temperature as % of bake times with data you can trust for consistency and comparative recipe transfer between lines and oven types. And, so easy to use, training is accomplished in one or two profile passes and quality assurance runs are apt to be performed on schedule. Qualifying the bake cycle for new varieties just got easier too!

FEATURES



Automatic S-Curve Profile



ECD North & South America
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Milwaukie, Oregon 97222-8825 U.S.A.
Tel: +1 503 659 6100/+1 800 323 4548
Fax: +1 503 659 4422
E-Mail: sales@ecd.com | Web: www.ecd.com

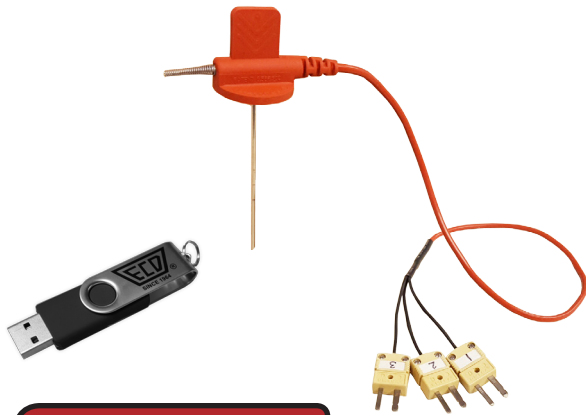
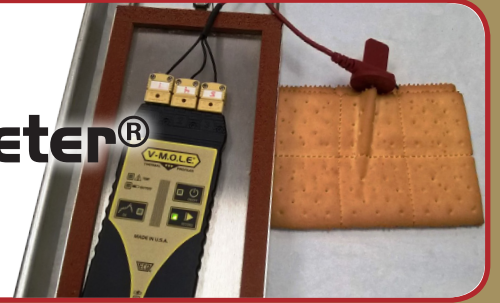
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• Top rated customer support • No-cost ECD Online Training • Award winning software •

For Bake Cycle
Perfection Every Time

Breadometer®



SYSTEM INCLUDES

- Breadometer®
- M.O.L.E.® MAP Software
- Quick Reference Guide
- Carry Case

Order ECD P/N: E55-2733-03

BENEFITS

- Optimize package weights without overage
- Optimize active ingredients benefits
- Produce consistently High Quality Product – at all locations
- Achieve optimum yield across all work shifts
- Rapidly transfer baking processes between ovens & locations
- Consistently finds the slowest to bake areas to optimize yield
- Reduce Energy usage by minimizing bake time
- Optimize output per BTU consumed
- Easy to use, works with industry standard M.O.L.E.® Profilers
- One piece probe, solves multiple thermocouples insertion difficulty
- Removes operator as a measurement variable
- Software saves analysis time with automatic S-Curve reporting
- MAP Automatically locates, Detect and Identifies: Start Temperature, Yeast Kill Temperature, Gelatinization, Arrival and End Temperature

WARRANTY

1 year parts and labor

PATENT

US Patent #: 8,556,502

FEATURES

V-M.O.L.E.® Compatible

Height:	82.5 mm (3.25") probe depth in dough 29.5 mm (1.16") body & grip above dough
Length:	69.8 mm (2.75")
Width:	37.4 mm (1.25")
Probe Weight:	45.3 grams (1.6 oz)
Probe material:	Stainless Steel
Temperature limit:	315°C (600°F) Maximum
Sensors:	3 Type K Themocouples
Lead wire:	45.7cm (18") long, PFA with Silicon jacket
Accuracy:	±1.1°C or 0.4% whichever is greater (Special Limits of error per ANSI MC 96.1)



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